

STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower

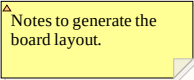
MB1848_HP

Table of contents

- Sheet 1: Project overview (this page)
- Sheet 2: Reference_Design_STM32WL_4L_IPD_ST_HP.SchDoc

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.



Open Platform License Agreement

The Open Platform License Agreement (“Agreement”) is a binding legal contract between you (“You”) and STMicroelectronics International N.V. (“ST”), a company incorporated under the laws of the Netherlands acting for the purpose of this Agreement through its Swiss branch 39, Chemin du Champ des Filles, 1228 Plan-les-Ouates, Geneva, Switzerland.

By using the enclosed reference designs, schematics, PC board layouts, and documentation, in hardcopy or CAD tool file format (collectively, the “Reference Material”), You are agreeing to be bound by the terms and conditions of this Agreement. Do not use the Reference Material until You have read and agreed to this Agreement terms and conditions. The use of the Reference Material automatically implies the acceptance of the Agreement terms and conditions.

The complete Open Platform License Agreement can be found on www.st.com/opla.

U_Top
Reference_Design_STM32WL_4L_IPD_ST_HP.SchDoc

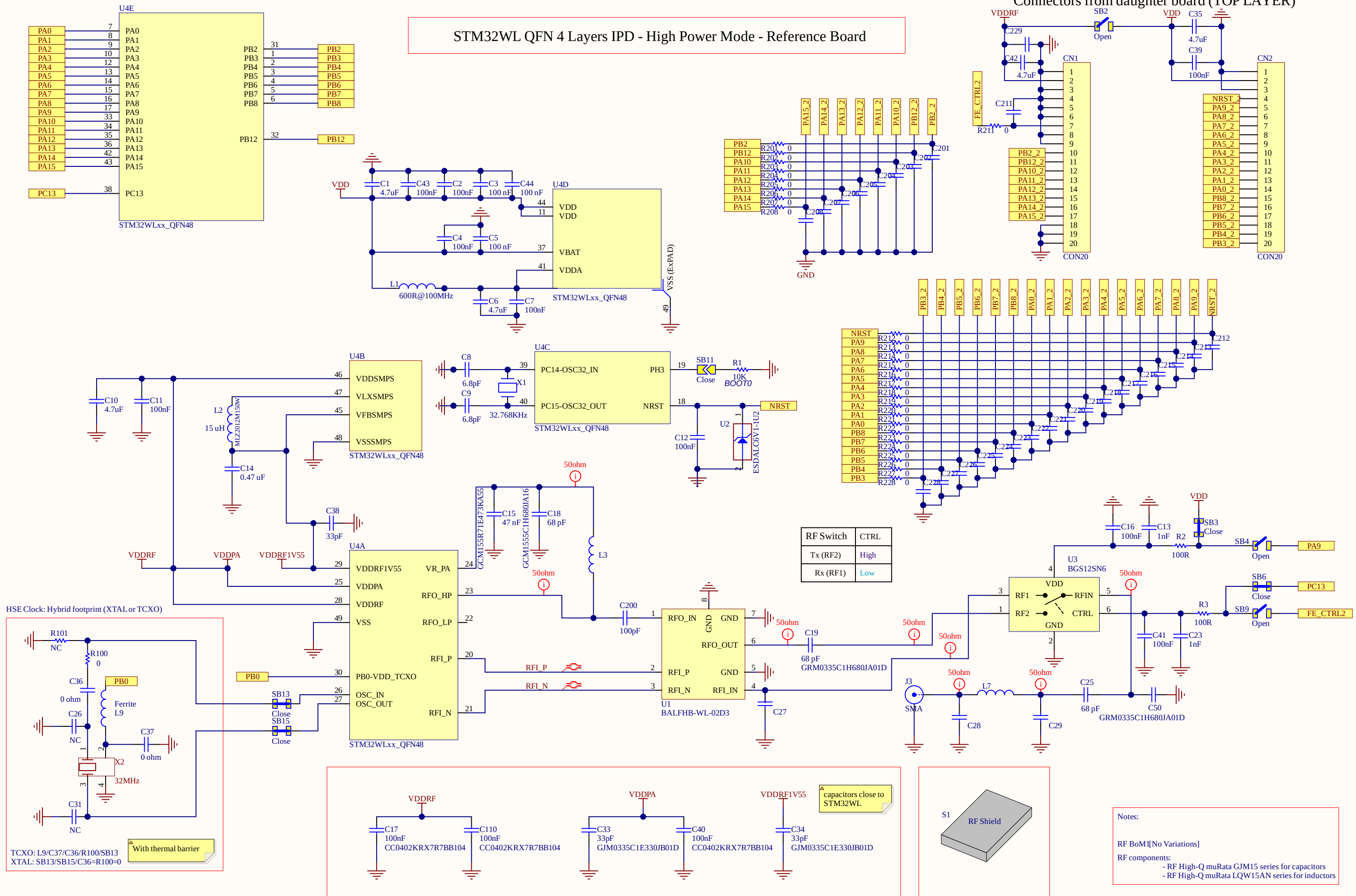


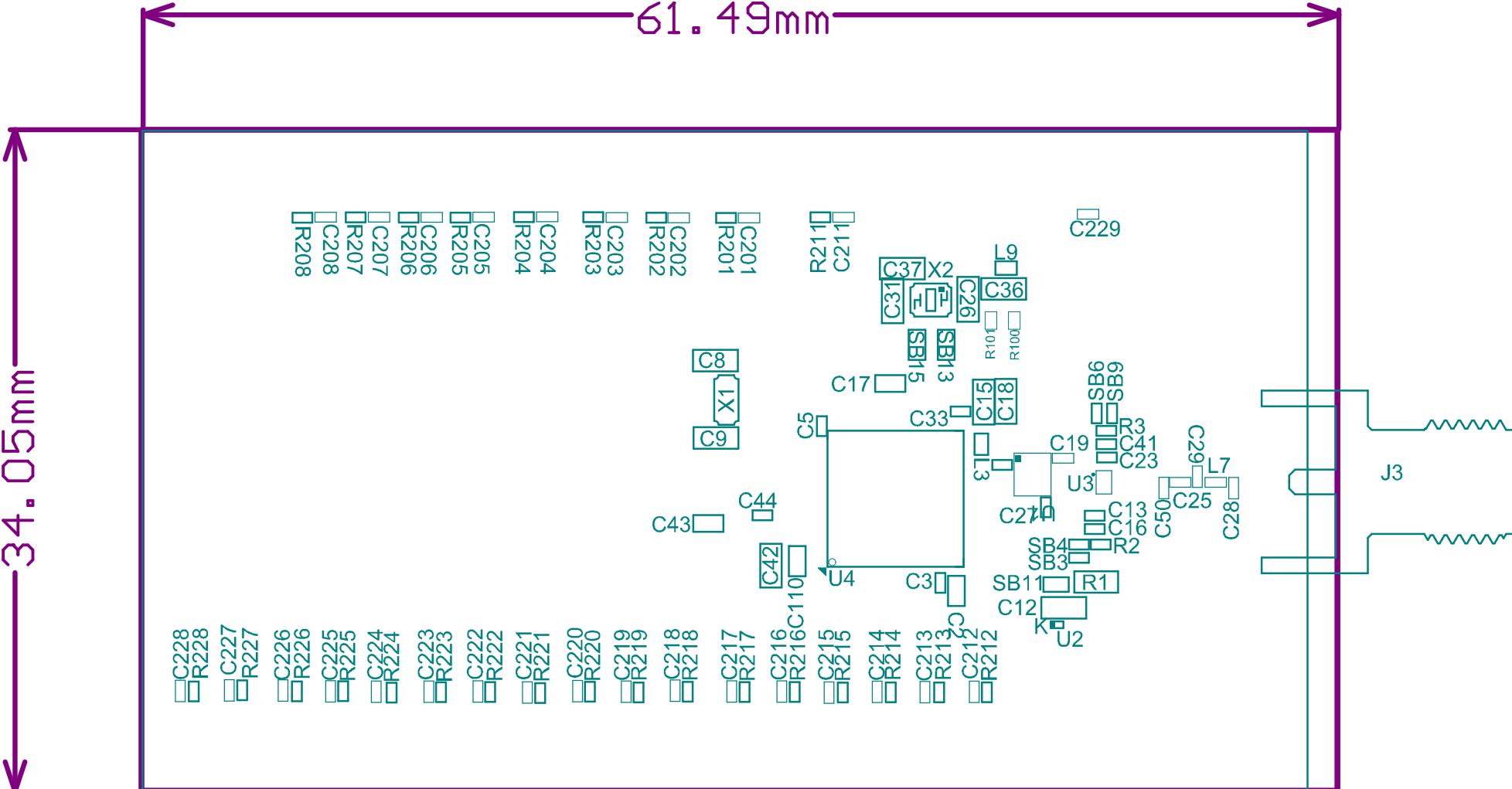
Title: Schematic sheet title to update		
Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPow		
Variant: [No Variations]		
Revision: A-01		Reference: MB1848_HP
Size: A4	Date: June 2022	Sheet: 1 of 2



STM32WL QFN 4 Layers IPD - High Power Mode - Reference Board

Connectors from daughter board (TOP LAYER)





Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower

Layer: **Top Assembly**

Gerber: **.GM14**

Variant: [No Variations]

Ref: MB1848_HP

Date: June 2022

Rev: A



